IN THE CLAIMS

1 (Previously Presented). A socket comprising:

an upper surface with a solder ball receiving aperture formed therein; and

an S-shaped spring contact arranged in said aperture, said contact adapted to make wiping electrical contact with a solder ball inserted into said aperture at a point spaced from the vertical center line of said solder ball.

Claim 2 (Canceled).

3 (Previously Presented). The socket of claim 1 wherein said spring contact is adapted to make wiping electrical contact with lands.

4 (Original). The socket of claim 1 wherein said S-shaped spring contacts include opposed contact arms, one of which extends upwardly and the other which extends downwardly.

5 (Previously Presented). The socket of claim 1 wherein socket includes a body, said body having a plurality of solder ball receiving apertures formed therein.

6 (Original). The socket of claim 5 including an alignment feature extending upwardly from said body to align a land grid array package with said socket.

7 (Previously Presented). The socket of claim 1 wherein said spring contact includes an upwardly extending arm to make contact with an integrated circuit package and a downwardly extending arm to make contact with an underlying circuit board.

8 (Original). The socket of claim 1 wherein said socket includes a body including an upwardly extending protrusion, said protrusion having a height less than the height of a solder ball for a ball grid array package.

9 (Previously Presented). The socket of claim 6 wherein said alignment feature is L-shaped.

10 (Original). The socket of claim 9 including two L-shaped alignment features opposed diagonally from one another on said socket.

11 (Previously Presented). An electronic device comprising:

a printed circuit board;

a socket coupled to said printed circuit board, said socket including a housing having an upper surface with a solder ball receiving aperture formed therein and an S-shaped spring contact aligned with said aperture to make wiping electrical contact with a solder ball inserted into said aperture at a point spaced from the vertical center line of said solder ball.

Claim 12 (Canceled).

13 (Previously Presented). The device of claim 12 wherein said spring contact includes opposed contact arms, one of which extends upwardly and the other which extends downwardly to contact said printed circuit board.

14 (Previously Presented). The device of claim 13 wherein said printed circuit board has a land engaged by said spring contact.

15 (Original). The device of claim 11 wherein said housing includes a protrusion on its upper surface to align a land grid array package with said housing.

16 (Previously Presented). The device of claim 15 wherein said protrusion is L-shaped.

17 (Previously Presented). The device of claim 16 including two L-shaped protrusions opposed diagonally from one another on said housing.

18 (Original). The device of claim 11 including a ball grid array package engaged on said socket housing.

19 (Original). The device of claim 11 including a land grid array package engaged on said socket housing.